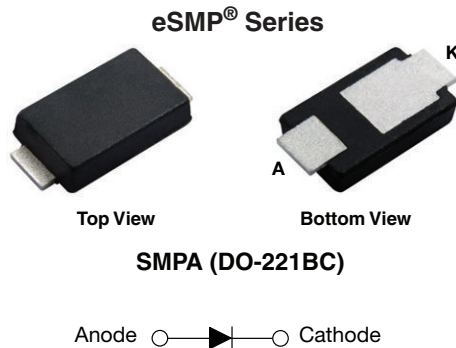




**THE DATASHEET OF  
V8PA10HM3/I**



# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier



## FEATURES

- Very low profile - typical height of 0.95 mm
- Ideal for automated placement
- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



## LINKS TO ADDITIONAL RESOURCES



## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial and automotive applications.

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	8.0 A
$V_{RRM}$	100 V
$I_{FSM}$	100 A
$V_F$ at $I_F = 8.0$ A ( $T_A = 125$ °C)	0.61 V
$T_J$ max.	150 °C
Package	SMPA (DO-221BC)
Circuit configuration	Single

## MECHANICAL DATA

**Case:** SMPA (DO-221BC)  
 Molding compound meets UL 94 V-0 flammability rating  
 Base P/N-M3 - halogen-free, RoHS-compliant  
 Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD22-B102  
 M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes cathode end

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V8PA10	UNIT
Device marking code		V810	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum DC forward current	$I_{F(AV)}$ <sup>(1)</sup>	8.0	A
	$I_{F(AV)}$ <sup>(2)</sup>	2.7	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	100	A
Operating junction and storage temperature range	$T_J, T_{STG}$	-40 to +150	°C

### Notes

- (1) Units mounted on 3 cm x 3 cm aluminum PCB  
 (2) Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 4.0\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.54	-	V
	$I_F = 8.0\text{ A}$			0.68	0.76	
	$I_F = 4.0\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.49	-	
	$I_F = 8.0\text{ A}$			0.61	0.69	
Reverse current	$V_R = 70\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.01	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		4.5	-	
	$V_R = 100\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.8	
		$T_A = 125\text{ }^\circ\text{C}$		9	24	
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	850	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width  $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)			
PARAMETER	SYMBOL	V8PA10	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	100	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	5	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP/dT_J < 1/R_{\theta JA}$
- (2) Free air, mounted on recommended PCB, 2 oz. pad area; thermal resistance  $R_{\theta JA}$  - junction to ambient
- (3) Units mounted on 3 cm x 3 cm aluminum PCB; thermal resistance  $R_{\theta JM}$  - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V8PA10-M3/I	0.032	I	14 000	13" diameter plastic tape and reel
V8PA10HM3/I <sup>(1)</sup>	0.032	I	14 000	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise specified)**

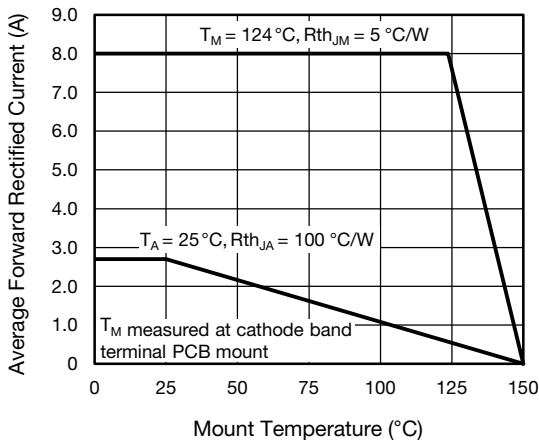


Fig. 1 - Maximum Forward Current Derating Curve

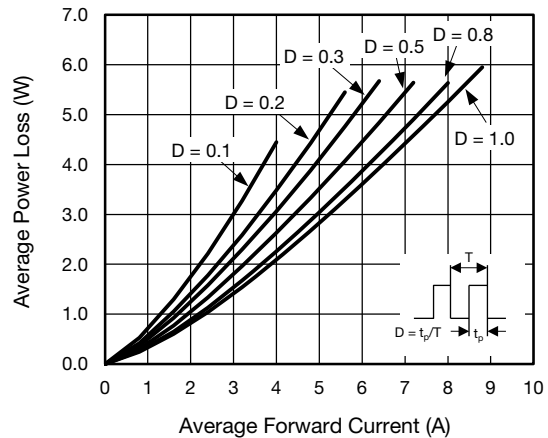


Fig. 2 - Forward Power Loss Characteristics

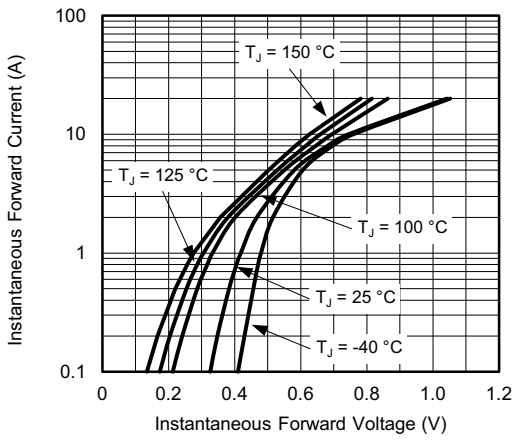


Fig. 3 - Typical Instantaneous Forward Characteristics

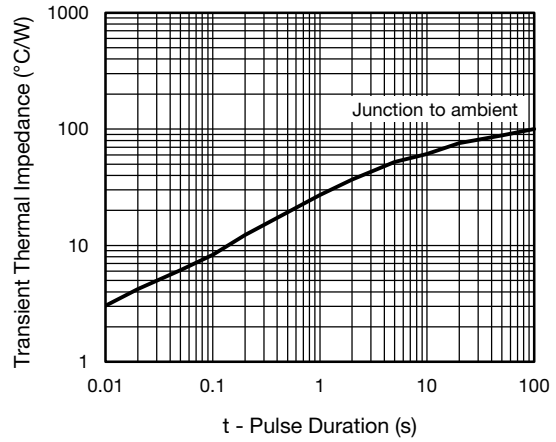


Fig. 6 - Typical Transient Thermal Impedance

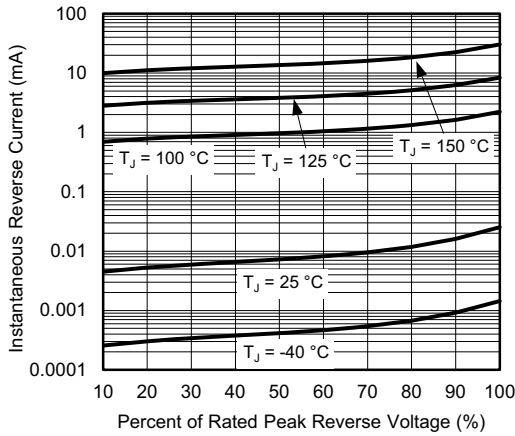


Fig. 4 - Typical Reverse Leakage Characteristics

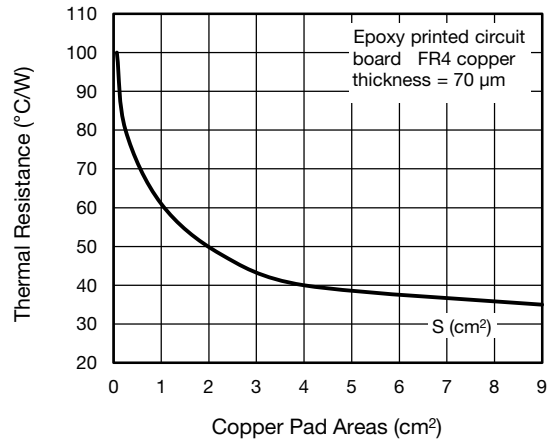


Fig. 7 - Thermal Resistance Junction to Ambient vs. Copper Pad Areas

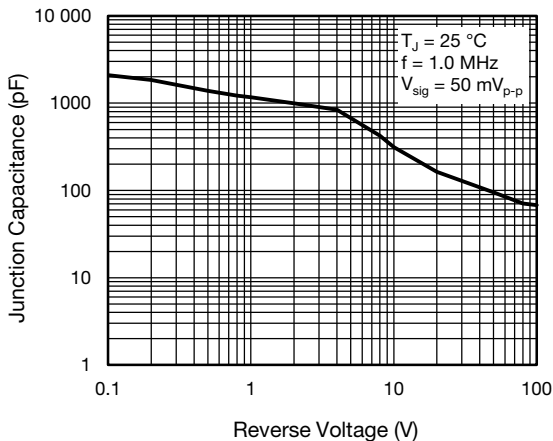
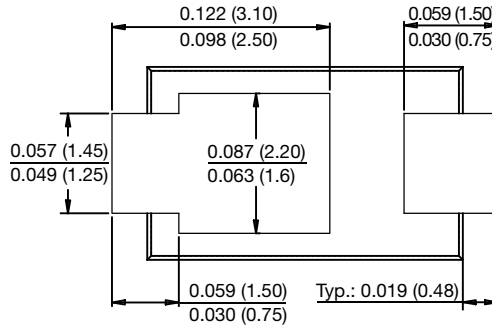
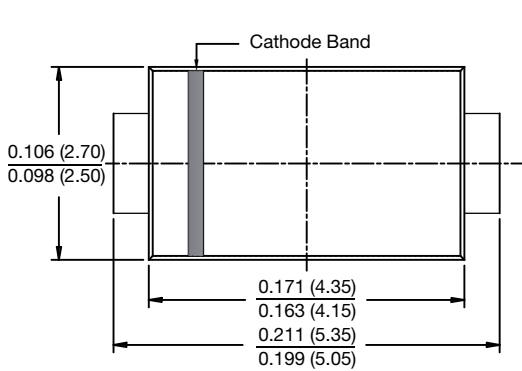


Fig. 5 - Typical Junction Capacitance

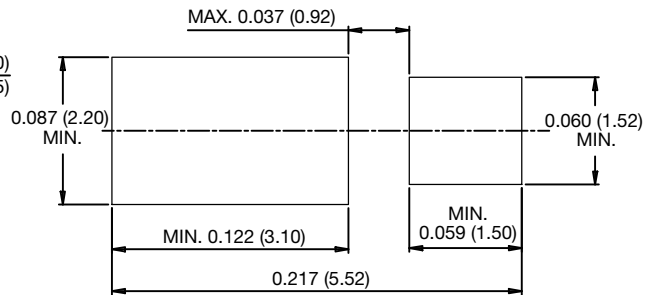
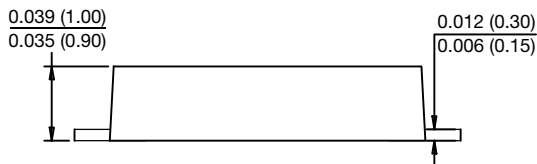


**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

**SMPA (DO-221BC)**



**Mounting Pad Layout**





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